

CLAIMS

- 1 1. A mounted electrophoretic display assembly, comprising:
 - 2 a flexible substrate;
 - 3 an electrical connection formed on said flexible substrate and having first and
 - 4 second contact pads spaced from one another;
 - 5 an electrophoretic display element in electrical communication with said first
 - 6 contact pad; and
 - 7 a control circuit mounted on said flexible substrate and in electrical communication
 - 8 with said second contact pad.
- 1 2. The display assembly of claim 1, wherein said control circuit is connected to said
2 second contact pad with a curable, electrically conductive thermoset.
- 1 3. The display assembly of claim 1, wherein said control circuit is connected to said
2 second contact pad with an electrically conductive ink.
- 1 4. The display assembly of claim 1, wherein said control circuit is connected to said
2 second contact pad with an electrically conductive paint.
- 1 5. The display assembly of claim 1, wherein said control circuit is connected to said
2 second contact pad by being removably mounted in a control circuit carrier that is in
3 electrical communication with said second contact pad.
- 1 6. The display assembly of claim 1 wherein said control circuit comprises an
2 electrophoretic display driver chip.
- 1 7. A method of manufacturing an electrophoretic display assembly, comprising the steps
2 of:
 - 3 providing a flexible substrate;

4 forming upon said substrate an electrical connection having a first contact pad and a
5 second contact pad spaced from one another;
6 mounting upon said substrate a control circuit in electrical communication with said
7 second contact pad; and
8 providing an electrophoretic display element in electrical communication with said
9 first contact pad.

1 8. The method of claim 7, wherein the step of forming upon said substrate an electrical
2 connection comprises a printing process.

1 9. The method of claim 7, wherein the step of providing an electrophoretic display
2 element comprises a printing process.

1 10. A method of manufacturing an electrophoretic display assembly, comprising the
2 steps of:
3 providing a first flexible substrate;
4 forming upon said first flexible substrate an electrical connection having a first
5 contact pad and a second contact pad separated from each other;
6 mounting on said first flexible substrate a control circuit in electrical
7 communication with said second contact pad;
8 providing a second flexible substrate;
9 disposing upon said second flexible substrate an electrophoretic display element;
10 and
11 disposing said first flexible substrate adjacent said second flexible substrate so that
12 said first contact pad addresses said electrophoretic display element.

1 11. The method of claim 10, wherein the step of disposing upon said second flexible
2 substrate an electrophoretic display element comprises a printing process.

1 12. The method of claim 10, wherein the step of disposing said first flexible substrate
2 adjacent said second flexible substrate further comprises a laminating process.